

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT5920817

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
GASPARD HIBLOT	01/15/2020
JULIEN JUSSOT	01/15/2020
GEERT VAN DER PLAS	01/07/2020
<b>RECEIVING PARTY DATA</b>	
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<b>Street Address:</b>	KAPELDREEF 75
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<b>State/Country:</b>	BELGIUM
<b>Postal Code:</b>	3001
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16716025
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	IMEC1108.001C1
<b>NAME OF SUBMITTER:</b>	ROSE M. THIESSEN
<b>SIGNATURE:</b>	/Rose M. Thiessen/
<b>DATE SIGNED:</b>	01/21/2020
	This document serves as an Oath/Declaration (37 CFR 1.63).
<b>Total Attachments: 5</b>	
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**COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.63(e))**

*Application Data Sheet filed previously or concurrently*

Docket No.: IMEC1101.001AUS

Page 1 of 5

Title: A METHOD FOR BONDING AND INTERCONNECTING SEMICONDUCTOR CHIPS

Inventors: Gaspard Hiblot, Julien Jussot, Geert Van der Plas

***Declaration***

This Declaration is directed to U.S. or International Application No. **16/716025**, filed December 16, 2019 and incorporating any amendments made thereto prior to the signature date of this Declaration.

As a named inventor, I declare that:

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

***Assignment from Inventors***

WHEREAS, **above-identified inventors** (individuals hereinafter "ASSIGNOR") invented certain new and useful improvements, technology, inventions, developments, ideas, ornamental designs, or discoveries related to **A METHOD FOR BONDING AND INTERCONNECTING SEMICONDUCTOR CHIPS** (collectively hereinafter referred to as the "Work") for which an application for Letters Patent in the United States (identified above) has been filed or prepared for filing with the United States Patent and Trademark Office (hereinafter the "Application"), and ASSIGNOR desires to assign or confirm assignment of the Work and the Application to the below identified Assignee.

AND WHEREAS, IMEC VZW, with its principal place of business at Kapeldreef 75, Leuven, Belgium, 3001 (hereinafter the "ASSIGNEE"), desires to acquire or confirm ownership of the entire right, title, and interest in and to the Application and the Work.

NOW, THEREFORE, for good and valuable consideration of which receipt is hereby acknowledged, ASSIGNOR hereby acknowledges that ASSIGNOR has sold, assigned, transferred, and set over, and by these presents does hereby sell, assign, transfer, and set over, unto said ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest throughout the world in and to the Application and the Work, including: all provisional applications relating to the Work and the Application; all nonprovisional applications claiming priority to aforementioned provisional(s) and/or the Application, including, all divisions, continuations, continuations-in-part, and reissues, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof; and all rights of priority under International Conventions and any related Letters Patent which may hereafter be granted or filed in any country or countries foreign to the United States, all extensions, renewals, and reissues thereof.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all related Letters Patent to the ASSIGNEE, its successors, legal representatives, and assigns.

AND ASSIGNOR DOES HEREBY sell, assign, transfer, and convey to ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the

**COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.63(e))**

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**Docket No.:** IMEC1101.001AUS

Page 2 of 5

**Title:** A METHOD FOR BONDING AND INTERCONNECTING SEMICONDUCTOR CHIPS

**Inventors:** Gaspard Hiblot, Julien Jussot, Geert Van der Plas

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rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said Letters Patent before or after issuance.

AND ASSIGNOR DOES HEREBY covenant and agree that ASSIGNOR will: communicate to said ASSIGNEE, its successors, legal representatives, and assigns any facts known to ASSIGNOR respecting the Work; testify in any legal proceeding; assist in the preparation of any other Patent Property relating to the Application and the Work or any improvements made thereto; sign/execute all lawful papers; authorize the filing of, execute, and make all rightful oaths and/or declarations in connection with the Application and the Work including any improvements made thereto, any patent applications filed therefrom, and any continuing application filed from any of the aforementioned applications; and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for the Work in all countries.

**COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.63(e))**

*Application Data Sheet filed previously or concurrently*

Docket No.: IMEC1101.001AUS

Page 3 of 5

Title: A METHOD FOR BONDING AND INTERCONNECTING SEMICONDUCTOR CHIPS

Inventors: Gaspard Hibiolt, Julien Jussot, Geert Van der Plas

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Legal Name of Inventor: Gaspard Hibiolt

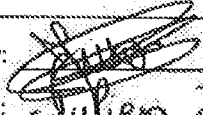
Signature: \_\_\_\_\_



Date: \_\_\_\_\_

15<sup>th</sup> Jan 2020

Witnessed by: \_\_\_\_\_



Witness Name (printed): \_\_\_\_\_

Julien JUSSOT

**COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.63(e))**

*Application Data Sheet filed previously or concurrently*

Docket No.: IMEC1101.001AUS

Page 4 of 5

Title: A METHOD FOR BONDING AND INTERCONNECTING SEMICONDUCTOR CHIPS

Inventors: Gaspard Hiblot, Julien Jussot, Geert Van der Plas

Legal Name of Inventor: Julien Jussot


Signature: \_\_\_\_\_



Date: \_\_\_\_\_

15/01/20

Witnessed by: \_\_\_\_\_



Witness Name (printed): \_\_\_\_\_

GASPARD HIBLOT

COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.53(e))

Application Data Sheet filed previously or concurrently

Docket No.: IMEC1101.001AUS

Page 5 of 5

Title: A METHOD FOR BONDING AND INTERCONNECTING SEMICONDUCTOR CHIPS

Inventors: Gaspard Hibliot, Julien Jussot, Geert Van der Plas

Legal Name of Inventor: Geert Van der Plas

Signature: \_\_\_\_\_

Witnessed by: \_\_\_\_\_

Date: \_\_\_\_\_

Witness Name (printed): \_\_\_\_\_

LINDA VANHEERBEEK

31963095

PATENT

RECORDED: 01/21/2020

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